



(3583)

2022/12/28

Safe Harbor Statement



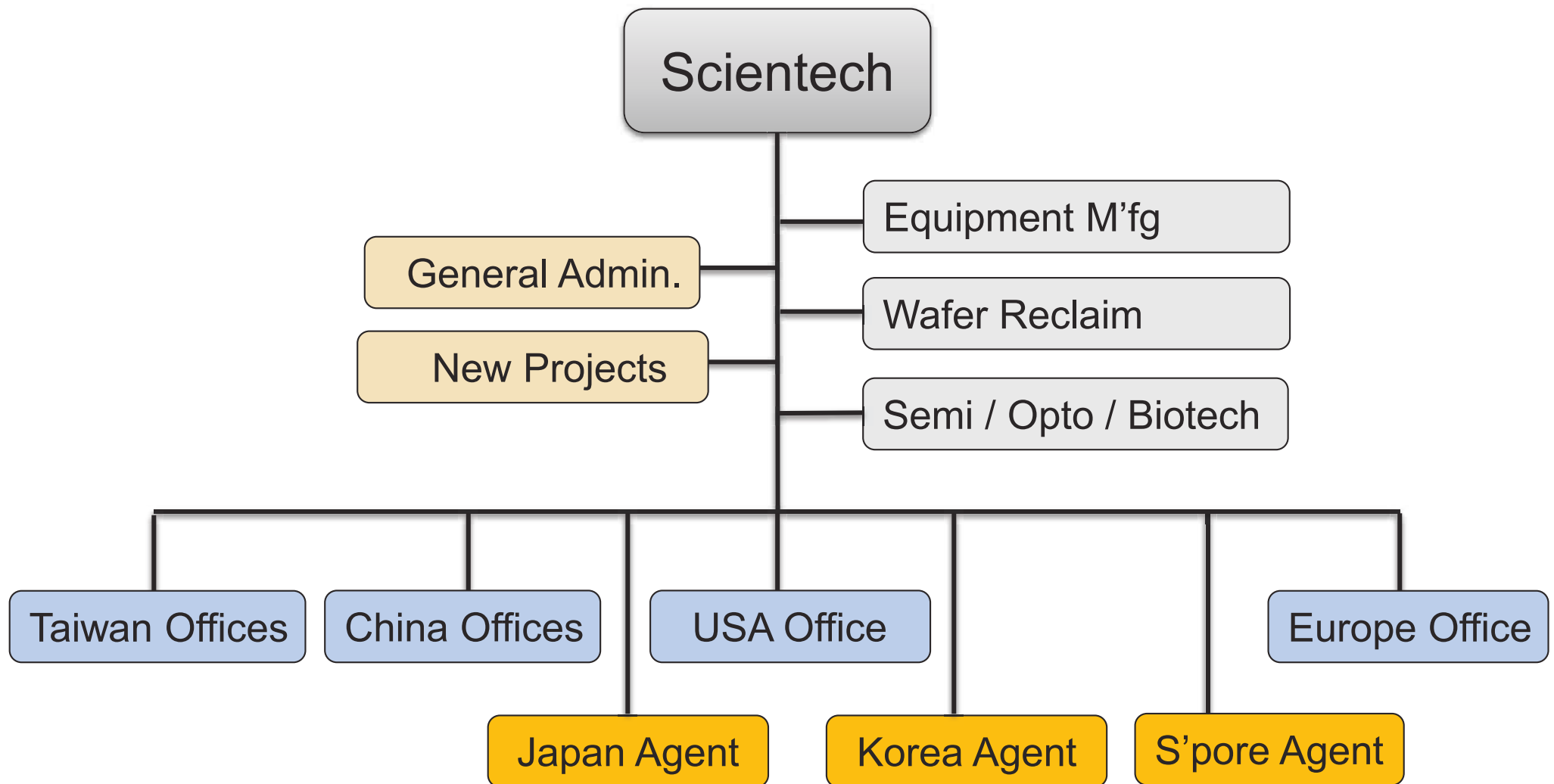
- This Presentation contains certain forward-looking statements that are based on current expectations and are subject to known and unknown risks and uncertainties that could cause actual results to differ materially from those expressed or implied by such statements.
- Except as required by law, we undertake no obligation to update any forward –looking statements, whether as a result of new information, future events or otherwise.

Sciencetech Corp (3583: TT)



Establishment	1979/10/17
Chairman & CEO	H.L. Hsieh
CEO	M.T. Hsu
Capital	NT\$ 811 Million
Revenue(2021)	NT\$ 4,684 Million (consolidated)
No. Employees	740 (Consolidated)
Location	1.Taiwan : Taipei, Hukou , Hsinchu, Tainan, Kaohsiung 2.Subsidiary Company : China(17 cities including Shanghai) , HK,USA , Europe(Austria) 3.Business Support : Japan,Singapore,South Korea
Products	Equipment Manufacturing 、 Wafer Reclaim 、 Trading(Agent/Distributor)

Organization



Business
Overview

Products

Corporate
Governance

Future
Prospect

Units : NT \$ M	2017	2018	2019	2020	2021	2022/Q3
Revenues	<u>3,539</u>	<u>3,988</u>	<u>3,949</u>	<u>3,580</u>	<u>4,684</u>	<u>4,077</u>
Gross Profit	<u>1,251</u>	<u>1,448</u>	<u>1,384</u>	<u>1,456</u>	<u>1,667</u>	<u>1,508</u>
Operating Expenses	829	935	997	991	1,112	1,024
Operating Income	423	514	387	465	555	485
Other Income and Expenses	(8)	26	16	(76)	(31)	56
Income Before Tax	415	540	403	389	524	541
Net Income	328	418	323	305	420	425
EPS	<u>4.05</u>	<u>5.16</u>	<u>4.02</u>	<u>3.80</u>	<u>5.23</u>	<u>5.29</u>
Gross Margin	35%	36%	35%	41%	36%	37%
Operating Margin	12%	13%	10%	13%	12%	12%
Income Before Tax margin	12%	14%	10%	11%	11%	13%

Business Overview

22/Q3 Consolidated Income statement



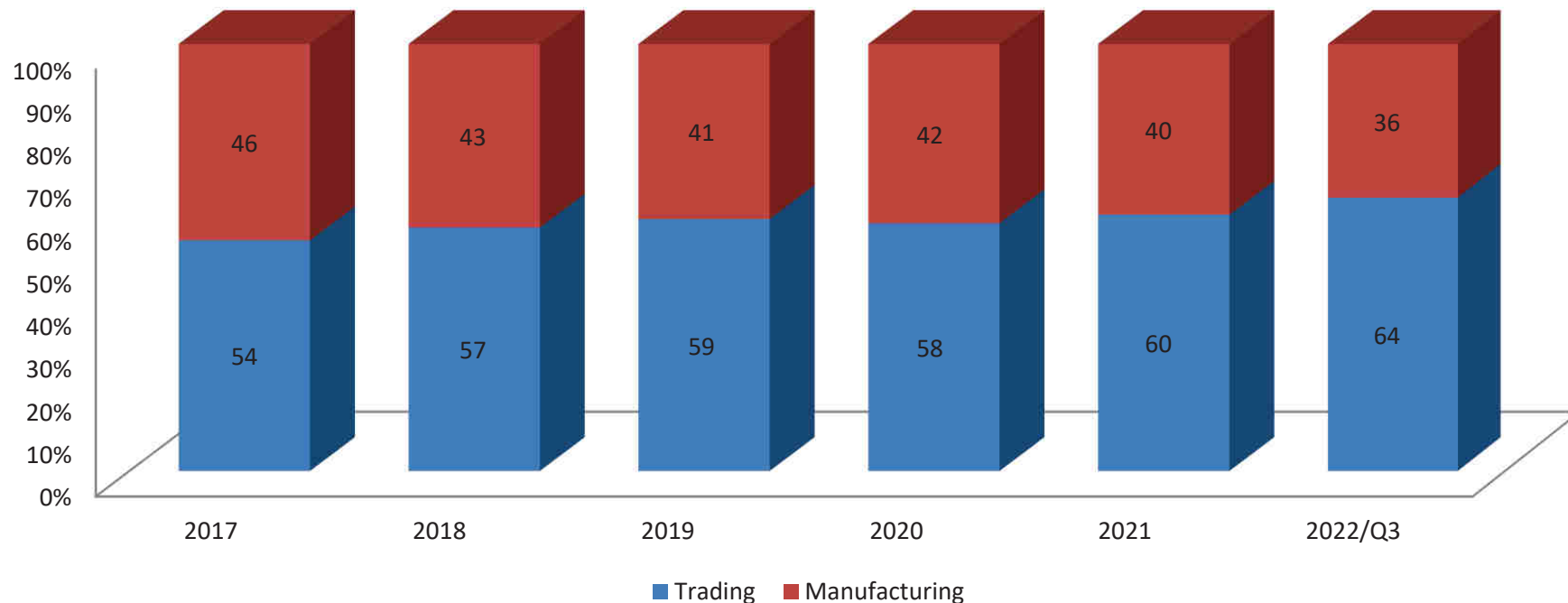
Units : NT \$ M	1Q21	2Q21	3Q21	1Q22	2Q22	3Q22	21/Q3	22/Q3	22/Q3 over22/Q3
Revenues	956	1,002	1,290	1,254	1,383	1,440	3,248	4,077	26%
Gross Profit	266	397	480	461	511	536	1,143	1,508	32%
Operating Expenses	253	219	288	332	338	354	760	1,024	35%
Operating Income	13	178	192	129	173	183	383	485	27%
Other Income and Expenses	24	-8	-22	26	3	28	-6	57	-1045%
Income Before Tax	37	170	170	155	176	211	377	542	44%
Net Income	20	147	130	121	152	152	297	425	43%
EPS	0.25	1.84	1.61	1.51	1.89	1.89	3.7	5.29	43%
Gross Margin	27.80%	39.60%	37.20%	36.80%	36.90%	37.20%	35.20%	37.00%	+1.8ppt
Operating Margin	1.40%	17.80%	14.90%	10.30%	12.50%	12.70%	11.80%	11.90%	+0.1ppt
Income Before Tax margin	3.90%	17.00%	13.20%	12.40%	12.70%	14.60%	11.60%	13.30%	+1.7ppt

Business Overview

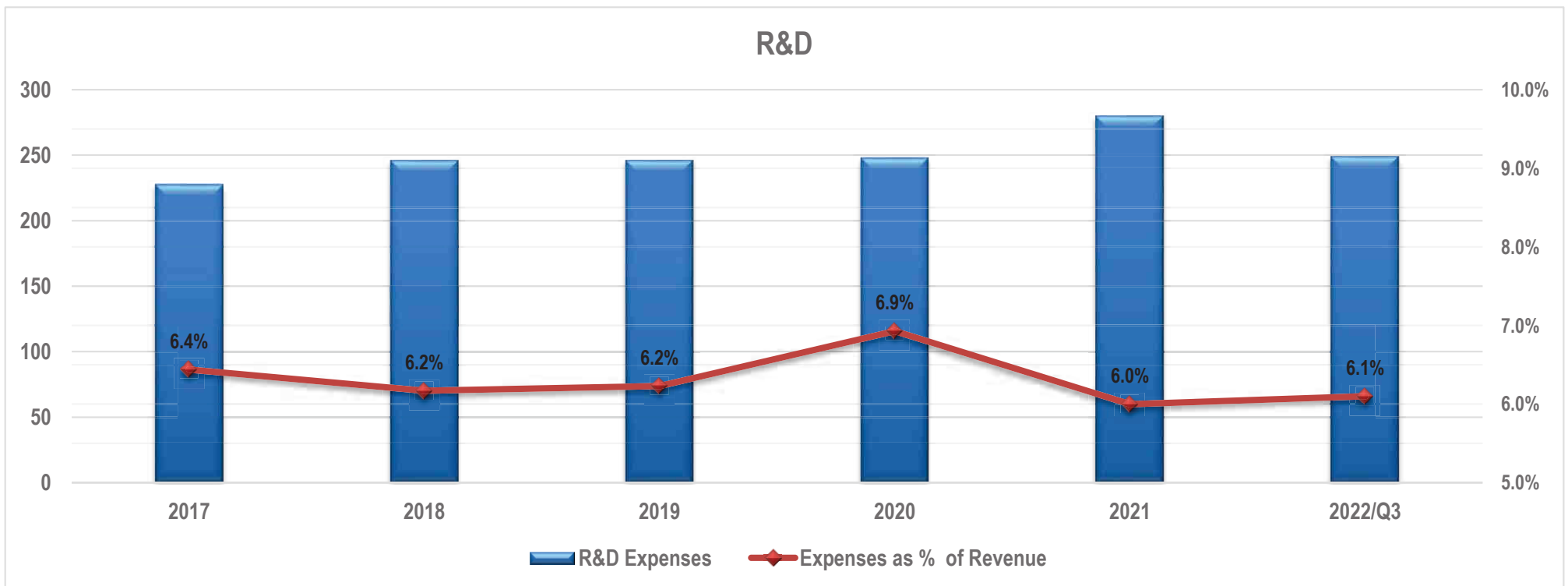
Products Mix



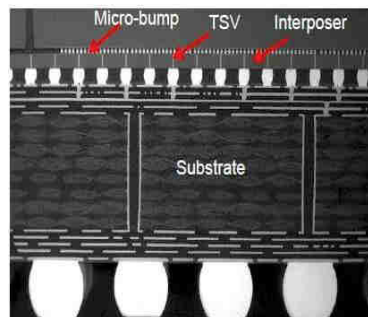
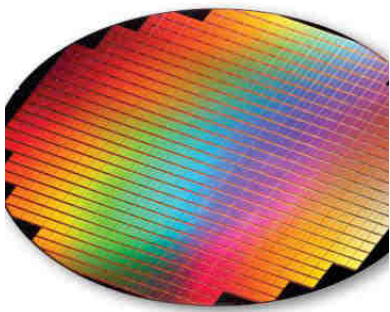
Units : %	2017	2018	2019	2020	2021	2022/Q3	Gross Margin
Trading	54	57	59	58	60	64	Below Average
Manufacturing	46	43	41	42	40	36	Above Average



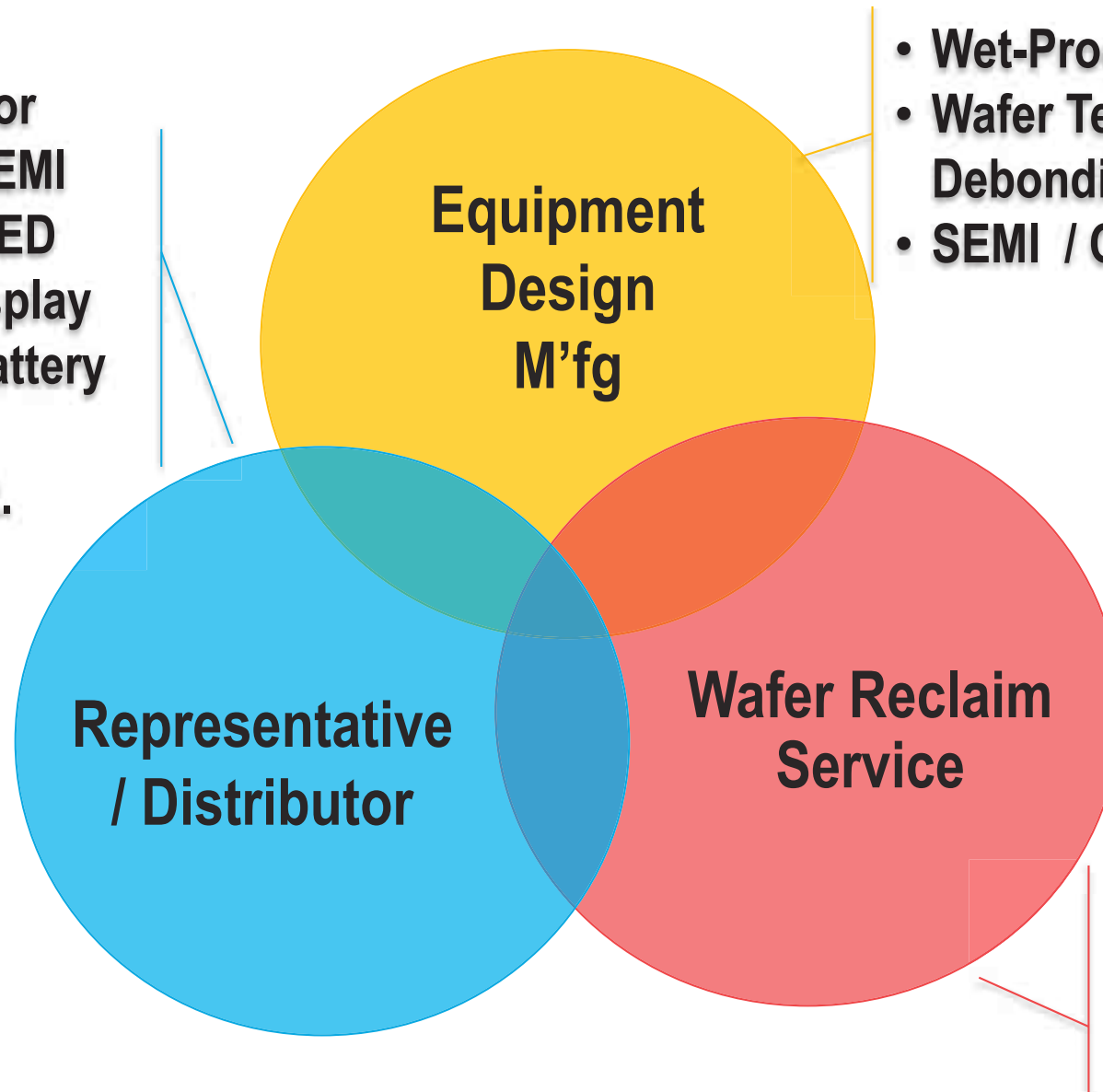
Units : NT \$ M	2017	2018	2019	2020	2021	2022/3Q
R&D Expenses	228	246	246	248	280	249
Expenses as % of Revenue	6.4%	6.2%	6.2%	6.9%	6.0%	6.1%



- Industries which we serve:
 - Semiconductor (Front-End and Advanced Packaging)
 - Compound Semiconductor
 - LED / Mini LED / Micro LED
 - Flat Panel Display (TFT-LCD, AMOLED, Touch Panel)
 - Solar Cell / Battery
 - Biotech / Chemistry Analysis / Scientific Instrument,...



- Semiconductor
- Compound SEMI
- LED / Micro LED
- Flat Panel Display
- Solar Cell / Battery
- Biotech
- Scientific Inst.



- Wet-Process Tools
- Wafer Temporary Bonding Debonding System
- SEMI / Compound / LED

- 12" Si Wafer
- 6" SiC Wafer

- Sciencetech Corp.



- 12" Wafer Reclaim

- ◆ Capacity: 120K→140K
→160K/ Month
- ◆ Cu and Non-Cu Process

- SiC Post Slicing Process and Reclaim

- ◆ Capacity: 800 / Month



- **Sciencetech Corp.**



SCIENTECH

- **Wet-Bench / Single-Wafer Wet Process Equipment**
- **Applications:**
 - ◆ Advanced Packaging Process
 - ◆ Semiconductor Front-End Process
 - ◆ Compound Semiconductor
 - ◆ Microelectromechanical Systems (MEMS)
 - ◆ High-End LED Fully-Automatic Advanced Process



- **Sciencetech Corp.**

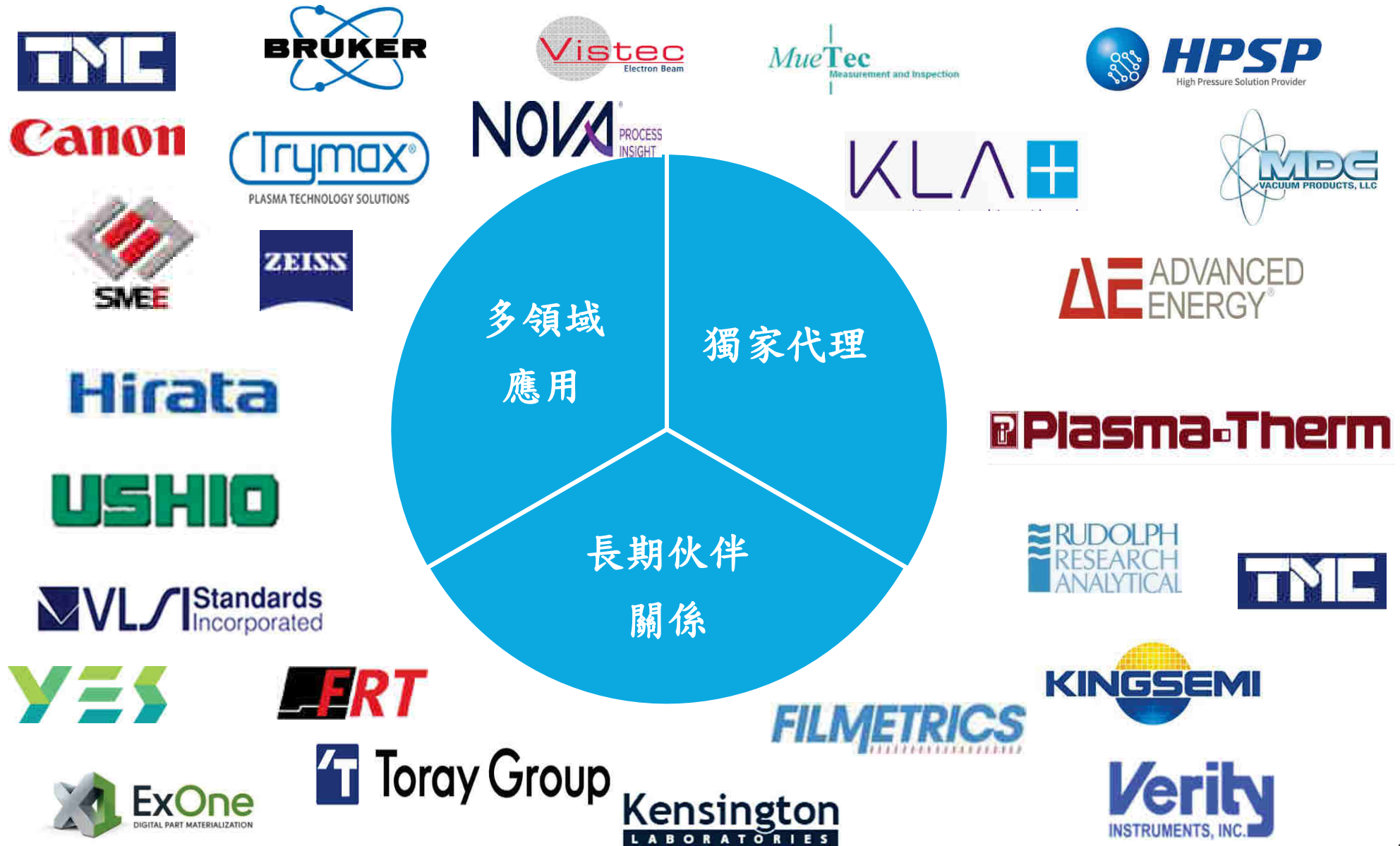


- **Temporary Bonding Debonding System (TBDB)**
- **Application: IGBT Power Device, Advanced Packaging for Semiconductor and LED**
 - ◆ Temporary Bonding System
 - ◆ Temporary Debonding System
 - ◆ Release Layer Formation System
 - ◆ Carrier (Glass) Recycling System



Products

Trading (Agent/Distributor)



Initial Certification

2014/5/27

Valid Date :

2020/5/28 ~ 2023/5/27



Issue 4. Certified since

2010/3/24

Valid Date :

2019/4/30 ~ 2022/4/30



Issue 3. Certified since

2019/4/30

Valid Date :

2019/4/30 ~ 2022/4/30



Issue 1. Certified since

2019/11/20

Valid Date :

2019/11/20 ~ 2022/11/19



Issue 1. Certified since

2021/09/29

Valid Date :

2021/09/29 ~ 2024/09/28



ISO9001

ISO14001

ISO45001

ISO27001
Information
Security

ISO22301
BCM


Taiwan Intellectual Property Management System

台灣智慧財產管理規範 (TIPS) 驗證登錄證書
Certificate of Taiwan Intellectual Property Management System

貴公司所建置之智慧財產管理制度，通過台灣智慧財產管理規範 (TIPS) 推行體系之驗證，特此證明。相關登錄事項如下：

一、公司名稱：辛耘企業股份有限公司
二、受證部門：全公司
三、受證地址：新竹縣新埔鄉中華路 18 號
四、證書編號：TIPS-2013-corp-008
五、有效期限：2021/12/31
六、受證類別：☒專利 ☒商標 ☐著作權 ☐營業秘密 ☐積體電路佈局
排除適用：☐無
七、驗證類別：☒AA 級 ☐A 級 (2016 年版)

驗證師：呂正華

Certificate of Compliance

This is to certify that the Intellectual Property Management System of the following organization has been verified and fulfilled the requirements of TIPS.

1. Company Name: Sciencetech Corporation
2. Registered Department: All Company
3. Registered Address: No. 18, Zhonghua Rd., Hukou Township, Hainchi County, 30352, Taiwan (R.O.C.)
4. Number of Registration: TIPS-2013-corp-008
5. Date of Expiration: December 31, 2021
6. Items: ☒ Patent ☒ Trademark ☐ Copyright ☐ Trade Secret
☐ Integrated Circuit Layout
Exclusion: None
7. Certification Level: ☒ AA ☐ A (2016)

Issued on: December 10, 2013
Issued by: Department of Intellectual Property Management, SCIENTECH

Richard Lee

Q & A



Thank You!